

[Previous Doc](#) [Next Doc](#) [Go to Doc#](#)
[First Hit](#)



Generate Collection

L8: Entry 101 of 109

File: DWPI

Apr 25, 2003

DERWENT-ACC-NO: 2003-856564

DERWENT-WEEK: 200380

COPYRIGHT 2005 DERWENT INFORMATION LTD

TITLE: Copper conductive-paste composition for electronic components, comprises organic vehicle in which resin is blended such that it does not remain as carbon on copper powder

PRIORITY-DATA: 2001JP-0312190 (October 10, 2001)

Search Selected

Search ALL

Clear

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<input type="checkbox"/> JP 2003123533 A	April 25, 2003		007	H01B001/22

INT-CL (IPC): H01 B 1/22; H01 B 13/00; H01 G 4/12; H05 K 1/09; H05 K 3/12

ABSTRACTED-PUB-NO: JP2003123533A

BASIC-ABSTRACT:

NOVELTY - Copper conductive-paste composition comprises copper powder, glass powder, organic vehicle containing resin and a solvent, and a fine-powder of stannous oxide, stannic oxide, indium oxide, vanadium oxide and/or zinc oxide. The resin is blended in organic vehicle such that it does not remain as carbon on copper powder when the composition is bake-processed in an inert atmosphere.

DETAILED DESCRIPTION - INDEPENDENT CLAIMS are also included for the following:

- (1) manufacture of copper conductive-paste composition; and
- (2) electronic component.

USE - For electronic component (claimed), and electrodes.

ADVANTAGE - The copper conductive-paste composition eliminates the necessity of oxygen dope and fine adjustment. The copper conductive-paste composition has a high industrial value.

[Previous Doc](#) [Next Doc](#) [Go to Doc#](#)

Hit List

[Clear](#)[Generate Collection](#)[Print](#)[Fwd Refs](#)[Bkwd Refs](#)[Generate OACS](#)

Search Results - Record(s) 1 through 1 of 1 returned.

☐ 1. Document ID: JP 2003123533 A

L5: Entry 1 of 1

File: JPAB

Apr 25, 2003

PUB-NO: JP02003123533A

DOCUMENT-IDENTIFIER: JP 2003123533 A

TITLE: COPPER CONDUCTOR PASTE COMPOSITION, ITS MANUFACTURING METHOD AND ELECTRONIC PARTS USING THE SAME

PUBN-DATE: April 25, 2003

INVENTOR-INFORMATION:

NAME

COUNTRY

ISHIYAMA, NAOKI

INT-CL (IPC): H01 B 1/22; H01 B 13/00; H01 G 4/12; H05 K 1/09; H05 K 3/12

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a copper conductor paste composition, a manufacturing method and electronic parts using the copper conductor paste composition dispensing with doping of oxygen and fine adjustment by allowing a baking method to be adopted in an inert atmosphere to form a conductor pattern or a terminal electrode on a ceramic board or a laminated ceramic capacitor.

SOLUTION: In this copper conductor paste composition comprising Cu powder A, glass powder B and an organic vehicle C, at least one kind of oxide fine powder selected out of SnO, SnO

COPYRIGHT: (C) 2003, JPO

Full	Title	Citation	Front	Review	Classification	Date	Reference	Abstract	Claims	Drawings
------	-------	----------	-------	--------	----------------	------	-----------	----------	--------	----------

[Clear](#)[Generate Collection](#)[Print](#)[Fwd Refs](#)[Bkwd Refs](#)[Generate OACS](#)

Term	Documents
JP-2003123533-A	1
JP-2003123533-AS	0
JP-2003123533-A.DID..JPAB.	1
(JP-2003123533-A.DID.).JPAB.	1